

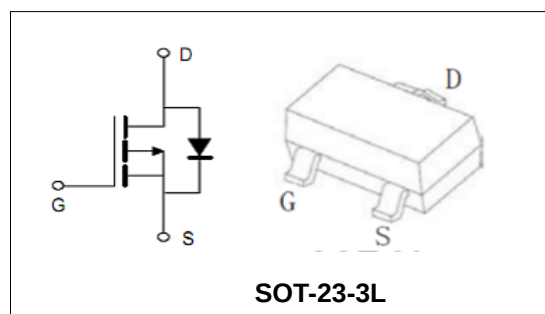
**-30V/-4.1A P-Channel Enhancement Mode MOSFET****Features**

- Advanced trench process technology
- High Density Cell Design For Ultra Low On-Resistance

|                 |      |    |
|-----------------|------|----|
| BVDSS           | -30  | V  |
| ID              | -4.1 | A  |
| RDSON@VGS=-10V  | 40   | mΩ |
| RDSON@VGS=-4.5V | 53   | mΩ |

**Applications**

- Low Side Load Switch
- Battery Switch
- Optimized for Power Management Applications for Portable Products, such as Aeromodelling, Power bank, Brushless motor, Main board , and Others

**Order Information**

| Product | Package   | Marking | Reel Size | Reel    | Carton    |
|---------|-----------|---------|-----------|---------|-----------|
| PT3407  | SOT-23-3L | A7sHB   | 7inch     | 3000PCS | 180000PCS |

**Absolute Maximum Ratings**

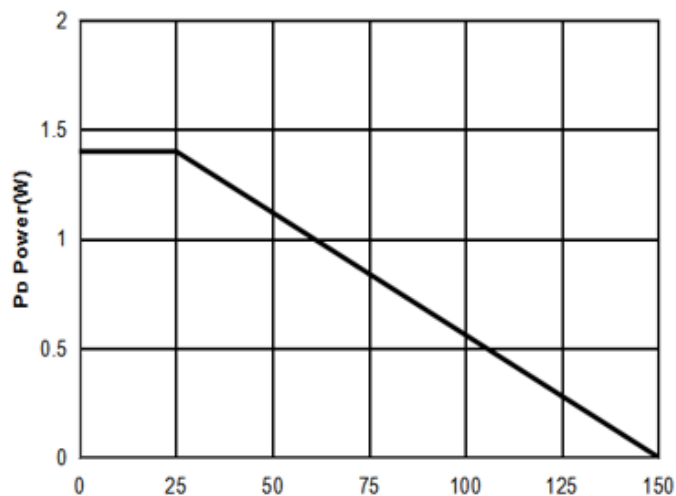
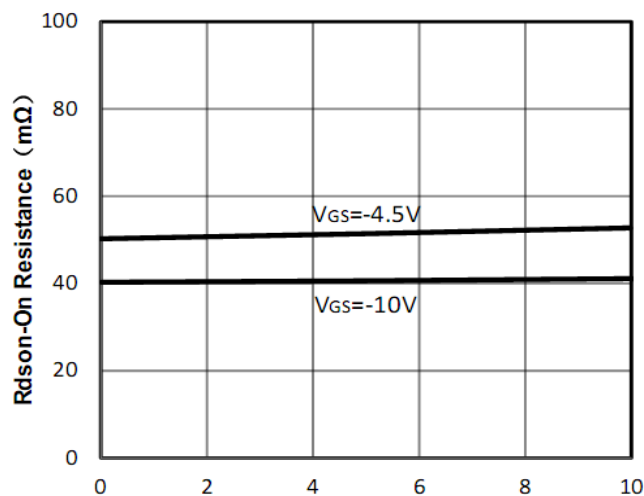
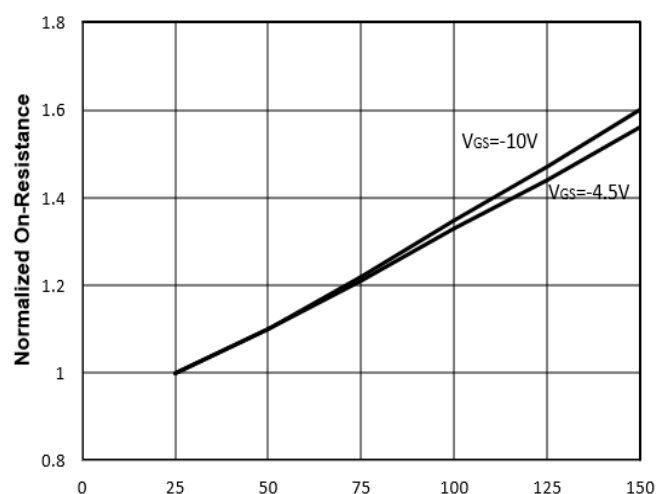
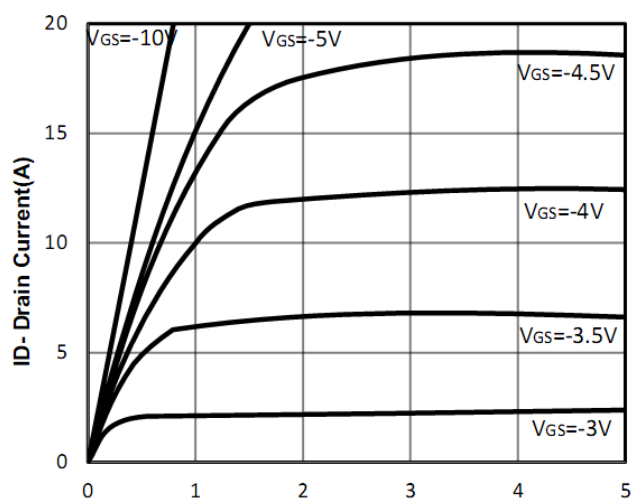
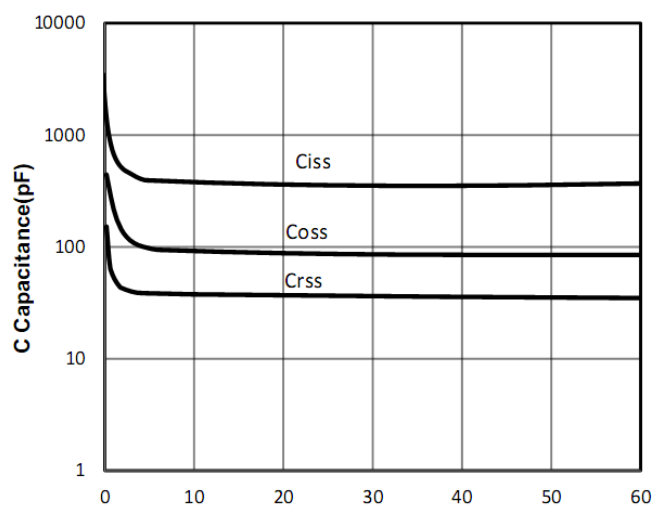
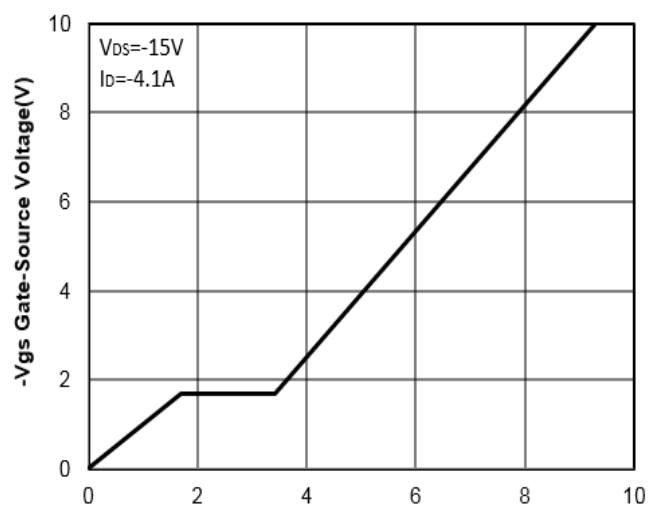
| Symbol                                          | Parameter                                  |                  | Rating       | Unit |
|-------------------------------------------------|--------------------------------------------|------------------|--------------|------|
| Common Ratings (TC=25°C Unless Otherwise Noted) |                                            |                  |              |      |
| V <sub>(BR)DSS</sub>                            | Drain-Source Breakdown Voltage             |                  | -30          | V    |
| V <sub>GS</sub>                                 | Gate-Source Voltage                        |                  | ±20          | V    |
| T <sub>J</sub>                                  | Maximum Junction Temperature               |                  | 150          | °C   |
| T <sub>STG</sub>                                | Storage Temperature Range                  |                  | -55 to 150   | °C   |
| I <sub>S</sub>                                  | Diode Continuous Forward Current           | TA =25°C         | -2.6         | A    |
| Mounted on Large Heat Sink                      |                                            |                  |              |      |
| I <sub>DM</sub>                                 | Pulse Drain Current Tested (Silicon Limit) | (Note1) TA =25°C | -20          | A    |
| I <sub>D</sub>                                  | Continuous Drain current                   | TA =25°C         | -4.1         | A    |
| P <sub>D</sub>                                  | Maximum Power Dissipation                  | TA =25°C         | 1.4          | W    |
| R <sub>θJA</sub>                                | Thermal Resistance Junction-to-Ambient     |                  | (Note2) 89.2 | °C/W |

**-30V/-4.1A P-Channel Enhancement Mode MOSFET**

| Symbol                                                                           | Parameter                                | Condition                                   | Min. | Typ.  | Max. | Unit |
|----------------------------------------------------------------------------------|------------------------------------------|---------------------------------------------|------|-------|------|------|
| Static Electrical Characteristics @ TJ = 25°C (unless otherwise stated)          |                                          |                                             |      |       |      |      |
| V <sub>(BR)DSS</sub>                                                             | Drain- Source Breakdown Voltage          | VGS=0V ID=-250μA                            | -30  | --    | --   | V    |
| I <sub>DSS</sub>                                                                 | Zero Gate Voltage Drain current          | VDS=-24V,VGS=0V                             | --   | --    | -1   | μA   |
| I <sub>GSS</sub>                                                                 | Gate-Body Leakage Current                | VGS=±20V,VDS=0V                             | --   | --    | ±100 | nA   |
| V <sub>GS(TH)</sub>                                                              | Gate Threshold Voltage                   | VDS=VGS,ID=-250μA                           | -1   | -1.5  | -3   | V    |
| R <sub>DS(ON)</sub>                                                              | Drain-Source On-State Resistance (Note3) | VGS=-10V, ID=-4.1A                          | --   | 40    | 55   | mΩ   |
|                                                                                  |                                          | VGS=-4.5V, ID=-3A                           | --   | 53    | 70   | mΩ   |
| Dynamic Electrical Characteristics @ TJ = 25°C (unless otherwise stated) (Note4) |                                          |                                             |      |       |      |      |
| C <sub>iss</sub>                                                                 | Input Capacitance                        | VDS= -15V,<br>VGS=0V,<br>F=1MHz             | --   | 551.5 | --   | pF   |
| C <sub>oss</sub>                                                                 | Output Capacitance                       |                                             | --   | 90.9  | --   | pF   |
| C <sub>rss</sub>                                                                 | Reverse Transfer Capacitance             |                                             | --   | 60.7  | --   | pF   |
| Q <sub>g</sub>                                                                   | Total Gate Charge                        | VDS= -15V,<br>ID= -4.1A,<br>VGS= -10V       | --   | 9.35  | --   | nC   |
| Q <sub>gs</sub>                                                                  | Gate-Source Charge                       |                                             | --   | 3.43  | --   | nC   |
| Q <sub>gd</sub>                                                                  | Gate-Drain Charge                        |                                             | --   | 1.7   | --   | nC   |
| Switching Characteristics (Note4)                                                |                                          |                                             |      |       |      |      |
| t <sub>d(on)</sub>                                                               | Turn-on Delay Time                       | VDD=-15V,<br>ID=-1A,<br>RG=15Ω,<br>VGS=-10V | --   | 10.8  | --   | nS   |
| t <sub>r</sub>                                                                   | Turn-on Rise Time                        |                                             | --   | 2.33  | --   | nS   |
| t <sub>d(off)</sub>                                                              | Turn-off Delay Time                      |                                             | --   | 22.53 | --   | nS   |
| t <sub>f</sub>                                                                   | Turn-off Fall Time                       |                                             | --   | 3.87  | --   | nS   |
| Source- Drain Diode Characteristics@ TJ = 25°C (unless otherwise stated)         |                                          |                                             |      |       |      |      |
| V <sub>SD</sub>                                                                  | Forward on voltage (Note3)               | IS=-2.6A,VGS=0V                             | --   | --    | -1.3 | V    |

Note:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec
3. Pulse Test: pulse width ≤ 300 us, duty cycle ≤ 2%.
4. Guaranteed by design, not subject to production testing.

**-30V/-4.1A P-Channel Enhancement Mode MOSFET****Typical Characteristics**Figure1: T<sub>j</sub> Junction Temperature (°C)Figure2: -I<sub>d</sub> Drain Current (A)Figure3: T<sub>j</sub> Junction Temperature (°C)Figure4: -V<sub>ds</sub> Drain-Source Voltage (V)Figure5: -V<sub>ds</sub> Drain-Source Voltage (V)Figure6: Q<sub>g</sub> Gate Charge (nC)

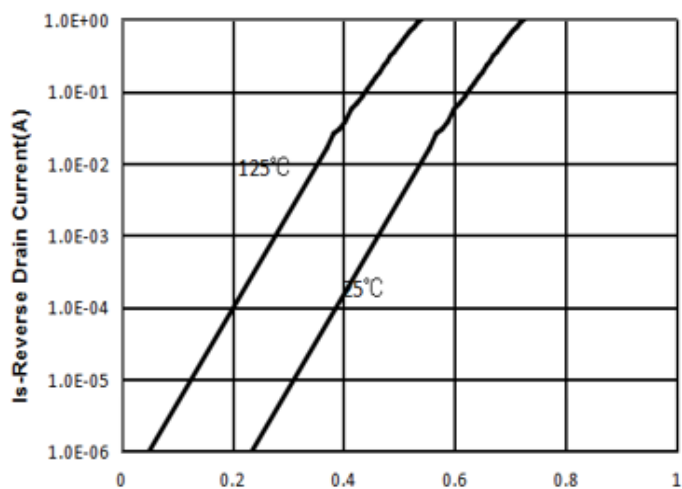
**-30V/-4.1A P-Channel Enhancement Mode MOSFET**

Figure7: -Vsd Source-Drain Voltage (V)

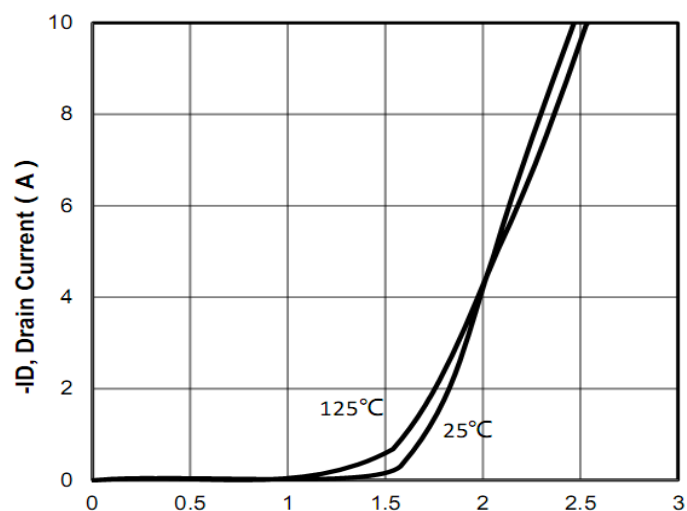


Figure8: -Vgs Gate-Source Voltage (V)

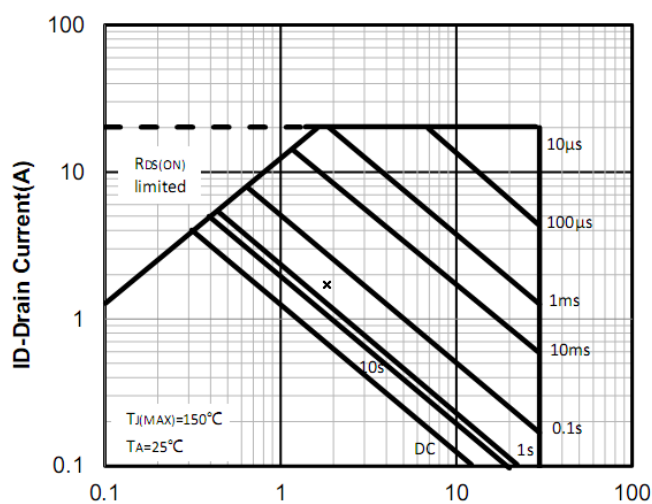


Figure9: -Vds Drain-Source Voltage (V)

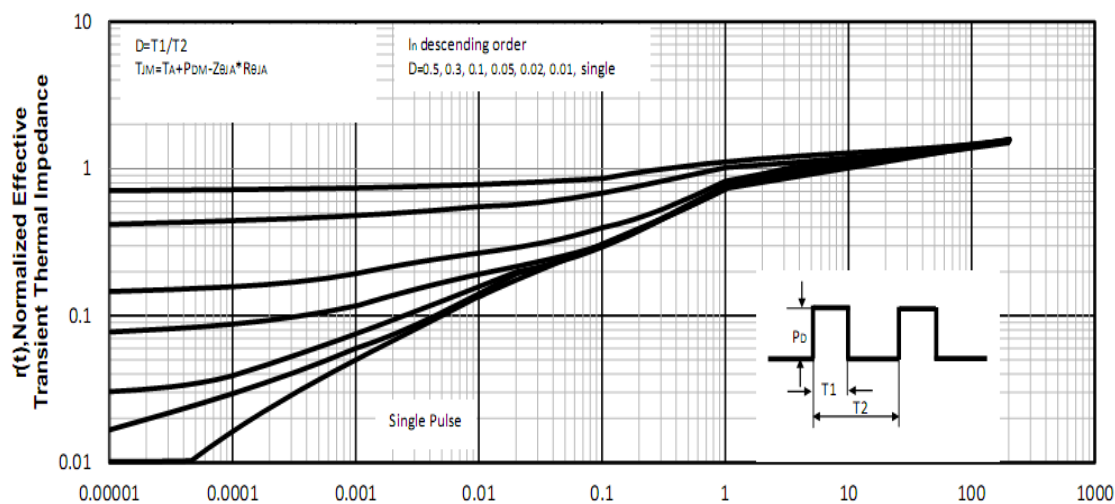
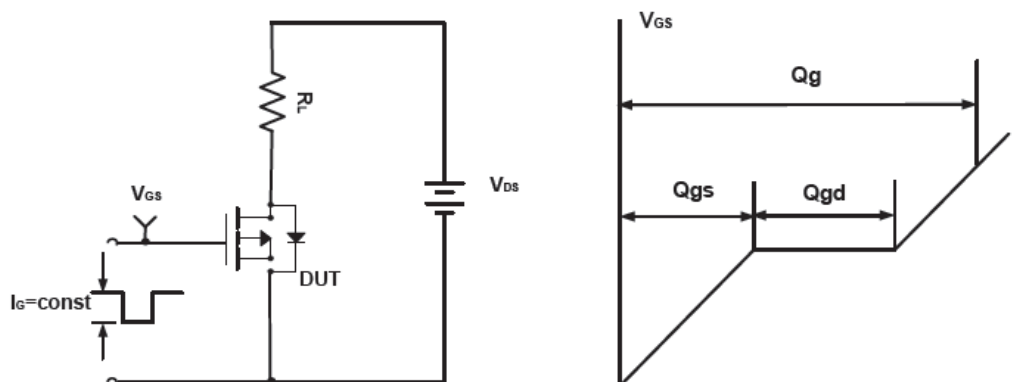
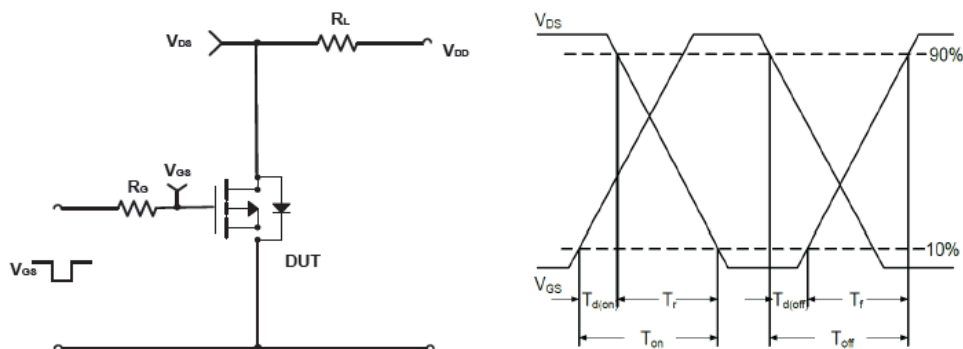
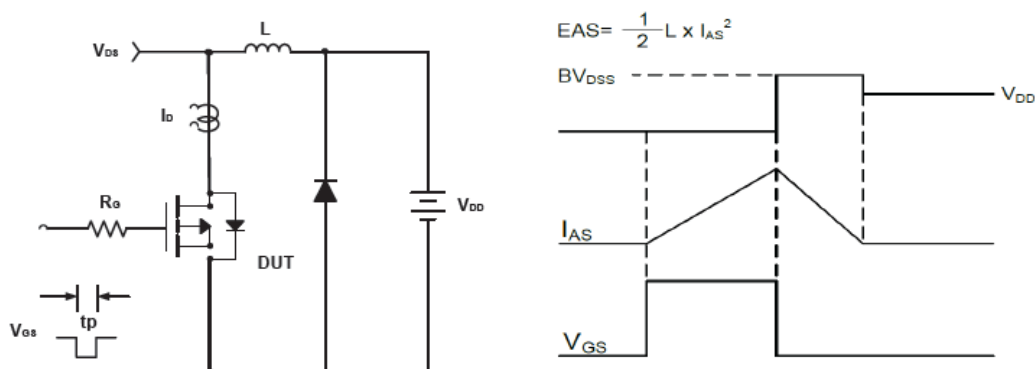
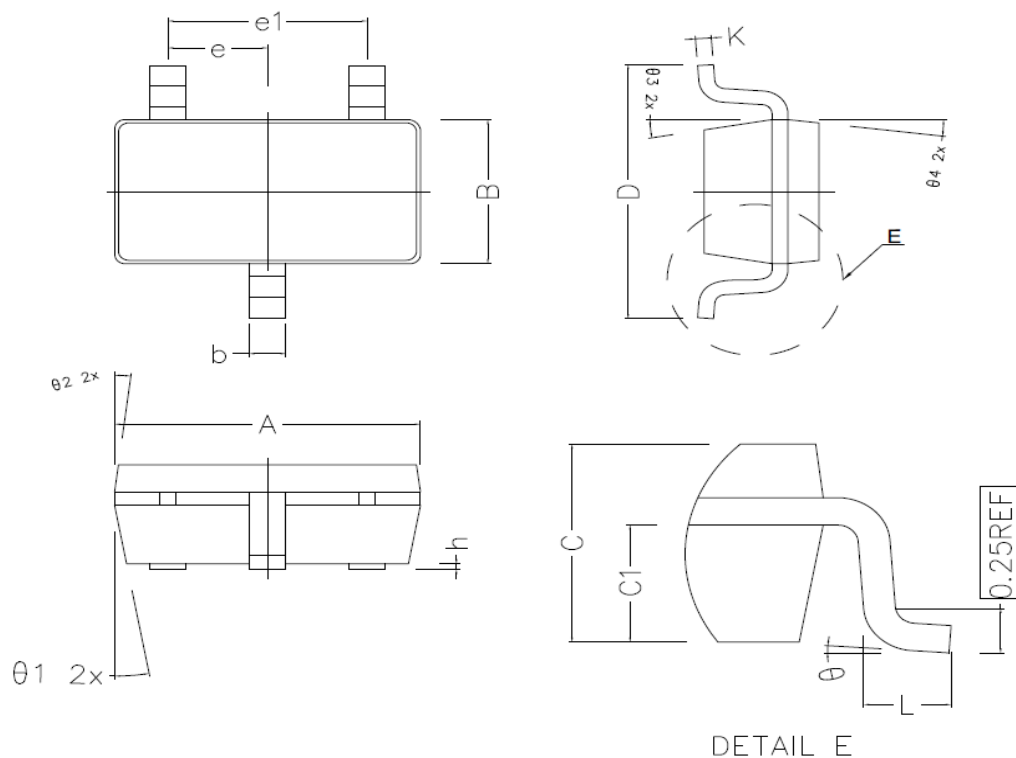


Figure10: Square Wave Pulse Duration (sec)

**Test Circuit and Waveform:**

**Figure A Gate Charge Test Circuit & Waveforms**

**Figure B Switching Test Circuit & Waveforms**

**Figure C Unclamped Inductive Switching Circuit & Waveforms**

**-30V/-4.1A P-Channel Enhancement Mode MOSFET****SOT-23-3 Package Outline Dimensions (Units: mm)**

| COMMON DIMENSIONS<br>(UNITS OF MEASURE IS mm) |           |        |       |
|-----------------------------------------------|-----------|--------|-------|
|                                               | MIN       | NORMAL | MAX   |
| A                                             | 2.820     | 2.920  | 3.020 |
| B                                             | 1.500     | 1.600  | 1.700 |
| C                                             | 1.050     | 1.100  | 1.150 |
| C1                                            | 0.600     | 0.650  | 0.700 |
| D                                             | 2.650     | 2.800  | 2.950 |
| L                                             | 0.300     | 0.450  | 0.600 |
| b                                             | 0.280     | 0.350  | 0.420 |
| h                                             | 0.020     | 0.050  | 0.100 |
| K                                             | 0.120     | —      | 0.230 |
| e                                             | 0.950TYPE |        |       |
| e1                                            | 1.900TYPE |        |       |
| $\theta_1$                                    | 10° TYPE  |        |       |
| $\theta_2$                                    | 7° TYPE   |        |       |
| $\theta_3$                                    | 10° TYPE  |        |       |
| $\theta_4$                                    | 7° TYPE   |        |       |
| $\theta$                                      | 0° ~ 8°   |        |       |